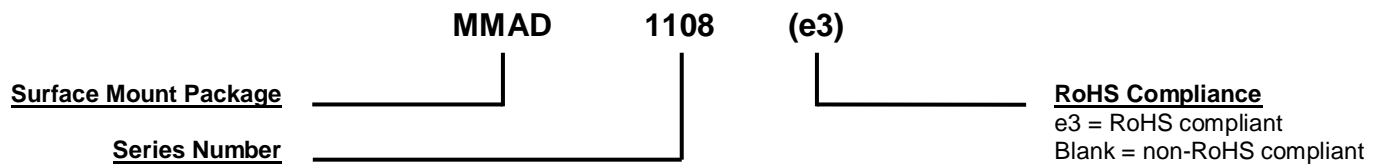


**MAXIMUM RATINGS**

Parameters/Test Conditions	Symbol	Value	Unit	
Junction and Storage Temperature	$T_J$ and $T_{STG}$	-55 to +150	°C/W	
Peak Working Reverse Voltage	$V_{RWM}$	75	V	
Repetitive Peak Forward Current (one diode)	$I_{FRM}$	400	mA	
Forward Surge Current		@ 8.3 ms	2	A
		@ 8/20 $\mu$ s	12	
Rated Average Power Dissipation (total package)	$P_{M(AV)}$	1500	mW	
Solder Temperature @ 10 s		260	°C	

**MECHANICAL and PACKAGING**

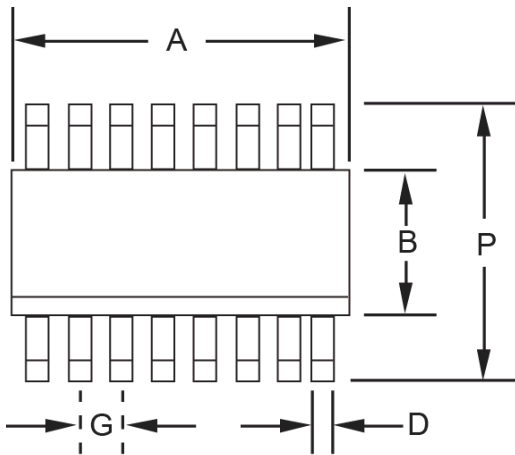
- CASE: Void-free transfer molded thermosetting epoxy body meeting UL94V-0 flammability classification.
- TERMINALS: Tin-lead or RoHS compliant annealed matte-tin plating solderable per MIL-STD-750 method 2026.
- MARKING: MSC logo, MMAD1108 or MMAD1108e3 and date code. Pin #1 is to the left of the dot or indent on top of package.
- DELIVERY option: Tape and reel or carrier tube. Consult factory for quantities.
- WEIGHT: Approximately 0.127 grams
- See [Package Dimensions](#) on last page.

**PART NOMENCLATURE**

**SYMBOLS & DEFINITIONS**

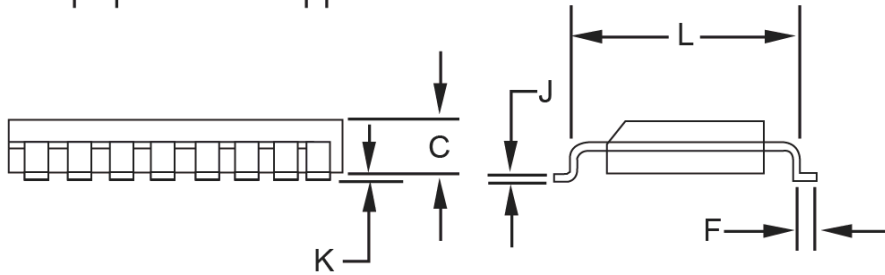
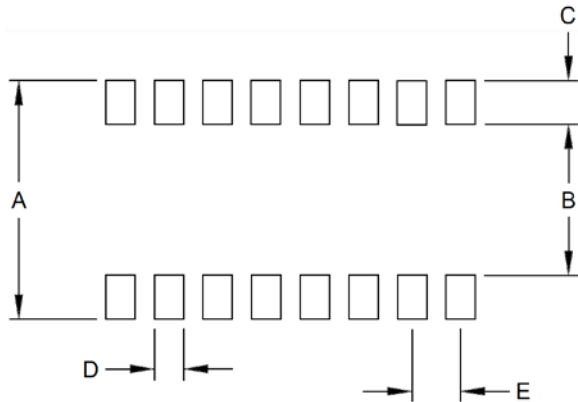
Symbol	Definition
$C_T$	Total Capacitance: The total small signal capacitance between the diode terminals of a complete device.
$I_R$	Maximum Leakage Current: The maximum leakage current that will flow at the specified voltage and temperature.
$V_{(BR)}$	Breakdown Voltage: The voltage across the device at a specified current $I_{(BR)}$ in the breakdown region.
$V_F$	Maximum Forward Voltage: The maximum forward voltage the device will exhibit at a specified current.
$V_{RWM}$	Working Peak Reverse Voltage: The maximum peak voltage that can be applied over the operating temperature range.

**ELECTRICAL CHARACTERISTICS @ 25 °C unless otherwise stated**

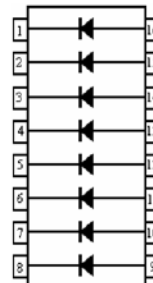
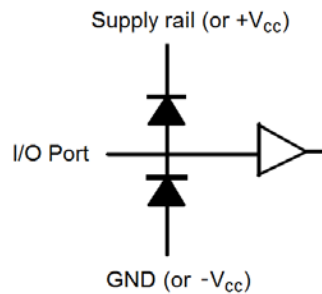
PART NUMBER	BREAKDOWN VOLTAGE	LEAKAGE CURRENT		LEAKAGE CURRENT		TOTAL CAPACITANCE	REVERSE RECOVERY TIME	FORWARD VOLTAGE	FORWARD VOLTAGE
	$V_{(BR)}$	$I_R$	$I_R$	$I_R$	$I_R$	$C_T$	$t_{rr}$	$V_F$	$V_F$
	@ $I_{(BR)} = 100 \mu A$	$T_A = 25 \text{ }^\circ C$	$T_A = 150 \text{ }^\circ C$	$T_A = 150 \text{ }^\circ C$	$T_A = 150 \text{ }^\circ C$	@ 0 V		$I_F = 10 \text{ mA}$	$I_F = 100 \text{ mA}$
	V	$\mu A$	$\mu A$	$\mu A$	$\mu A$	pF	ns	V	V
	MIN	MAX	@ $V_R$	MAX	@ $V_R$	TYP	MAX	MAX	MAX
MMAD1108 MMAD1108e3	90	0.200	20	300	20	1.5	5.0	1.00	1.20

**PACKAGE DIMENSIONS**


Ref.	Dimensions			
	Inch		Millimeters	
	Min	Max	Min	Max
A	0.358	0.398	9.09	10.10
B	0.150	0.158	3.81	4.01
C	0.053	0.069	1.35	1.75
D	0.011	0.021	0.28	0.53
F	0.016	0.050	0.41	1.27
G	0.050 BSC		1.27 BSC	
J	0.006	0.010	0.15	0.25
K	0.004	0.008	0.10	0.20
L	0.189	0.206	4.80	5.23
P	0.228	0.244	5.79	6.19


**PAD LAYOUT**


Ref.	Dimensions	
	Inch Typical	Millimeters Typical
A	0.275	7.0
B	0.155	4.0
C	0.060	1.52
D	0.024	0.6
E	0.050	1.270

**SCHEMATIC AND CIRCUIT**

**Figure 1**